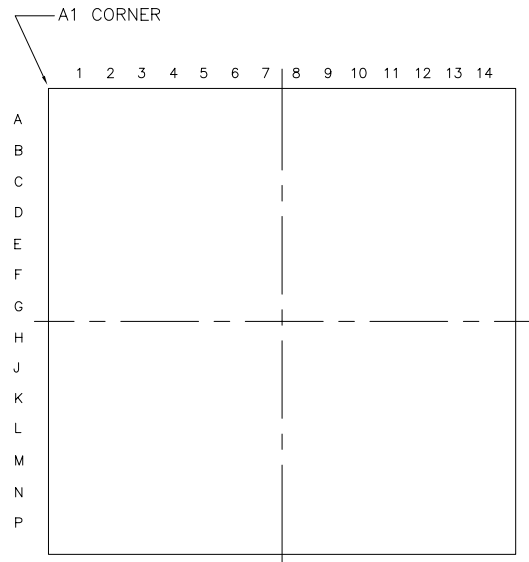
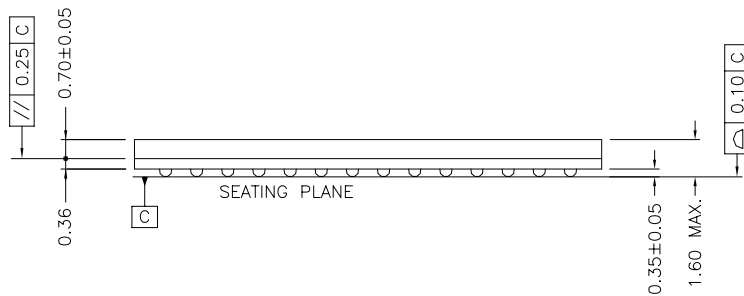
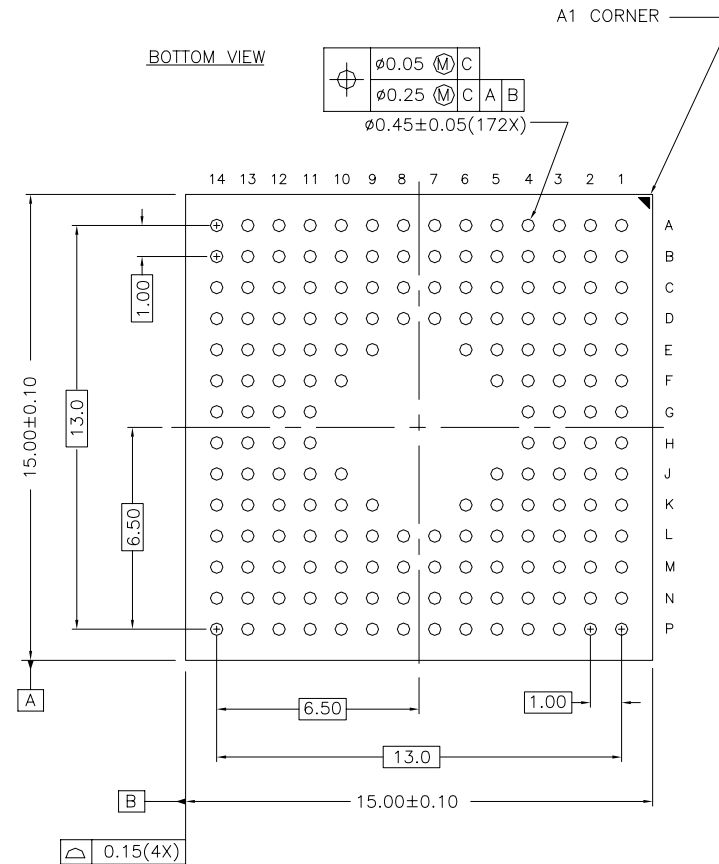


REVISIONS				
ZONE	REV	ECN	DESCRIPTION	DATE
	**	109473	NEW RELEASE	08/15/01
	*A	115632	ADD SUBSTRATE DIM./ ADD MOLD CAP DIM./ CHG. BALL HEIGHT DIM./ CHG. PKG. BODY TOLERANCE	05/14/02
	*B	397717	Change title and pkg thickness.	09/20/05

TOP VIEW



BOTTOM VIEW



PACKAGE WEIGHT - 0.6 grams

Jedec Publication 95, Design Guide 4.14

UNLESS OTHERWISE SPECIFIED		DESIGNED BY	DATE
ALL DIMENSIONS ARE IN MILLIMETERS		DRAWN	DATE
STANDARD TOLERANCES IN:		MLA	09/20/05
DECIMALS	±	CHK BY	DATE
XX	±	APPROVED BY	DATE
XXX	±	APPROVED BY	DATE
XXXX	±		
MATERIAL			
FINISH			



CYPRESS
SEMICONDUCTOR

TITLE			
172 FBGA (15x15x1.6mm) PKG. OUTL. FOR SINGLE or STACKED DIE			
SIZE	PART NO.	DWG NO.	REV
A	BB172SD	51-85146	*B
SCALE		SHEET	
5: 1		1 OF 1	